

PCN: V12-012-E47540-MK

Product Change Notice

Original Issue Date: 24 September, 2012 1st Revision Issue Date: 26 October, 2012

<u>Change Type:</u> New transceiver module design

Parts Affected:

8G Fibre Channel SFP+ SW, 850nm Multimode, -10 to +85°C

Current Avago Part Number	New Avago Part Number	
AFBR-57D7APZ	AFBR-57D9AMZ	
AFBR-57D7AMZ	AFBR-57D9AMZ	

Description and Extent of Change:

New module design with Avago designed IC (laser driver, EEPROM, limiting amplifier), TIA, moving pin housing with metal delatch release mechanism.

Reason for Change:

To improve supply assurance on critical piece parts. The new designs incorporate Avago designed silicon using Avago's foundry fabrication relationships. Enhanced mechanical design to improve module interaction with tight-fitted cages.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

There will be changes to the module form and fit, but customers are not expected to experience issues using it in the existing applications. The customers should expect no differences in functionality, quality and reliability. The device specification and manufacturing process will be same to the current products.

Effective Date of Change:

Product shipments using this change will begin on or after December 24th, 2012 (WW52) or earlier with customer approval. Timing of shipment will depend on customer demand, and inventory levels.

Support of Current Materials:

Avago plans to obsolete the listed current part numbers. Customers will have until February 1st, 2013 to place the last-time orders, and last-time ship date from Avago will be March 15th, 2013.

Recommended Actions to be Taken by Customer:

1. Module-level qualification is recommended. Avago will make samples available and will commence shipment of new 8G SW SFP+ products upon successful customer qualification after December 24th, 2012. Please return any response as soon as possible, but not to exceed 90 days.

2. Sample requests must specify the PCN # stated above and shall be placed by your Avago Technologies Field Sales Representative through the Avago Technologies FOMFGS ordering system.

Qualification Data:

Qualification report with 2,000-hour data is available.

Leg	Test	Reference	Stress Condition	S/S	Result
1	High Temperature Operating Life -1	GR-468-CORE Section 5.18	Tc = 85°C, Vcc = 3.3V	11	0 Failures @ 2000Hrs
2	High Temperature Operating Life -2	GR-468-CORE Section 5.18	Tc = 85°C, Vcc = 3.3V	11	0 Failures @ 2000hrs
3	High Temperature Storage**	GR-468-CORE	Ta = 85°C	11	0 Failures @ 2000hrs
4	Biased Damp Heat	MIL-STD-202 Method 103	Tc= 85oC, RH=85% Vcc=3.3V	11	0 Failures @ 1000hrs
5	Un-Biased Damp Heat	MIL-STD-202 Method 103	Ta= 85oC, RH=85%	11	0 Failures @ 1000hrs
6	Temperature Cycling	MIL-STD-883 Method 1010	Ta = -40°C to +100°C,	11	0 Failures @ 500Cyc
7a	Mechanical Vibration	MIL-STD-883 Method 2007A	20 – 2000Hz, 20 G 4min/cycle, 4cycle/axis, 3 axis, unmated	11	0 Failures
7b	Mechanical Shock	MIL-STD-883 Method 2002B	1500g (peak), 0.5ms, 5 pulses/surface, 6 surfaces, unmated	11	0 Failures
8a	Contact Discharge	IEC 61000-4-2	2KV, 4KV & 8KV 10 zaps on electrical faceplate on panel Live traffic	3	(not started)
8b	Air Discharge	IEC 61000-4-2	15000V Live Traffic	3	(not started)
9	ESD – HBM	JESD22-A114-B	As specified on product data sheet. Typically 2000V except for high speed pins that are typically 1000V	6	Completed with no failures

These changes have been reviewed and approved by Avago Technologies engineers and managers per Avago Technologies' procedure: Change Control and Customer Notification, A-5962-6052-80.

Please contact your Avago Technologies field sales engineer or Contact Center (<u>http://www.avagotech.com/contact/</u>) for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.